

# Nanotesla-field detectivity with hysteresis-free magnetic tunnel junctions

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Magnetic field sensors are required to show linear change of output voltage as magnetic field strength changes. For that, a few methods have been reported to stabilize the magnetization of the free layer ( $\vec{M}_{FL}$ ) orthogonal to that of the reference layer ( $\vec{M}_{RL}$ ), e.g. "2-step annealing" to induce exchange bias on RL by the first annealing and magnetic anisotropy on FL by second annealing or vice versa [1]. Firstly,  $\vec{M}_{RL}$  is defined by setting the direction of exchange-bias field ( $\vec{H}_{ex}$ ) through the 1<sup>st</sup> annealing in a uniformly magnetic field ( $\vec{H}$ ). Secondly, for SL; it is coupled with a thick layer of NiFe to induce a magnetic anisotropy field ( $\vec{H}_k$ ) having an orthogonal direction to  $\vec{H}_{ex}$  through the 2<sup>nd</sup> annealing [2]. However, NiFe has an fcc 111 texture and CoFeB (CFB) must acquire bcc out-of-plane 001 texture in order to achieve high TMR ratios. Thus, a dust layer of Ta is often introduced to improve the 001 texture of CFB. However, TMR is still influenced and no hysteresis-free curve is reported up to date [1-4]. Indeed, searching for alternative materials for the soft-magnetic layers is indispensable.

In this study, as shown in Fig. 1a, we incorporate an amorphous CoFeBTa (CFBT) as a soft-magnetic free layer which is ferromagnetically coupled with the CFB layer through the Ta (0.3 nm) insertion layer. Unlike the previous reports [1, 2], in our MTJ stack, the free-layer magnetic anisotropy was induced by the 1<sup>st</sup> annealing at 350°C and the exchange-bias on RL was set by the 2<sup>nd</sup> annealing at 200°C as clarified by arrows in Fig. 1b. By doing this, a cross-magnetic anisotropy between  $\vec{M}_{FL}$  and  $\vec{M}_{RL}$  is formed. Therefore,  $\vec{M}_{FL}$  changes with  $\vec{H}$  smoothly without abrupt changes, providing a hysteresis-free transfer curve with a small linear operating range ( $< 3$  mT) as shown in Fig. 2 (Red curve).

Furthermore, we systematically investigated the CFBT thickness dependence ( $t_{CFBT}$ ) of noise voltage for the proposed layer structure. All fabricated devices showed  $1/f$  noise behaviors with a strong magnetic-field dependence as shown in Fig. 3. The noise voltage is smaller in P ( $\mu_0 H \approx -5$  mT) and AP ( $\approx 5$  mT) states than that during the transition of magnetization between P and AP states. Moreover, the noise voltage increased as the bias voltage across junctions increased as shown in Fig 4. We evaluated the Hooge's parameter ( $\alpha_H$ ) from the  $1/f$  noise; MTJ having  $t_{CFBT} = 20$  nm giving rise to  $\alpha_H \approx 2.7 \times 10^{-8} \mu\text{m}^2$  at P state. Such smaller value than that reported elsewhere [2] for a single MTJ sensor is considered to be due to the hysteresis-free transfer curve in our MTJs. We studied also the magnetic field detectivity dependence on  $t_{CFBT}$  at 5 Hz as shown in Fig. 5. We found that a detectivity as low as 4 nT/Hz<sup>0.5</sup> is obtained for the sensor having  $t_{CFBT} = 20$  nm. Nevertheless, detectivity increased as  $t_{CFBT}$  increased.

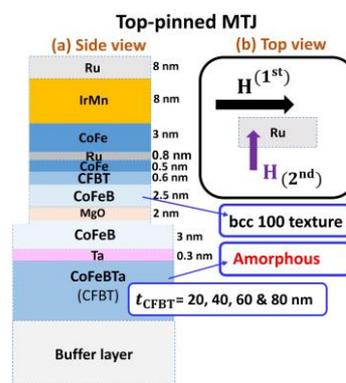


Fig. 1: The newly-proposed layer structure.

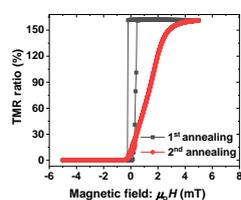


Fig. 2: Small field RH-loops showing the free layer transfer curve after 1<sup>st</sup>- & 2<sup>nd</sup>-annealing.

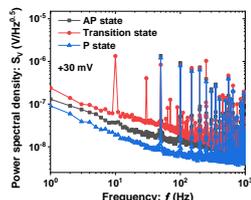


Fig. 3: Magnetic-field dependence on noise voltage of MTJ having  $t_{CFBT} = 20$  nm.

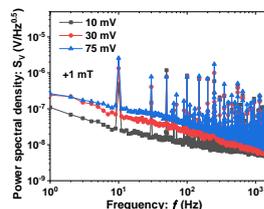


Fig. 4: Bias-voltage dependence on noise voltage of MTJ having  $t_{CFBT} = 20$  nm.

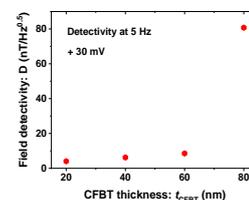


Fig. 5: Magnetic field detectivity dependence on  $t_{CFBT}$ .

## References

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